



Micro Commercial Components  
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## MC551-30

### Features

- Extremely Low VF
- Extremely thin package
- Low stored charge

### Mechanical Data

- Case: Molded plastic, JEDEC SOD-323
- Terminal : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : 0.000159 ounce, 0.0045 gram

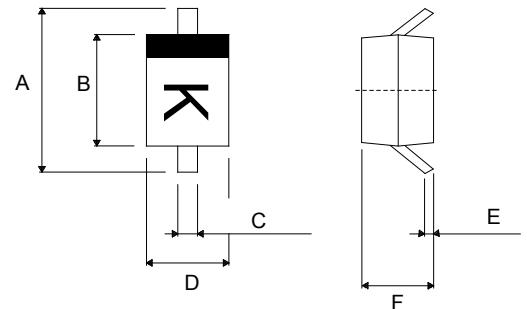
### Maximum Ratings

- Operating Junction Temperature: -40°C to +125°C
- Storage Temperature: -40°C to +125°C

MCC Catalog Number	Device Marking	Repetitive Peak Reverse Voltage	Continuous Reverse Voltage
MC551-30	K	30V	20V

## 0.5 Amp Surface Mount Schottky Barrier Diode 30 Volts

### SOD323

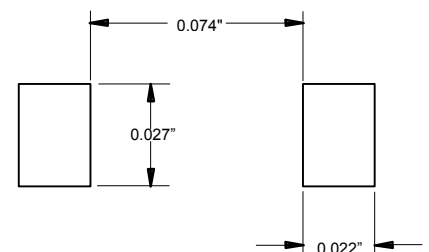


DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.091	.106	2.30	2.70	
B	.063	.071	1.60	1.80	
C	.010	.017	0.25	0.43	
D	.045	.053	1.15	1.35	
E	.004	.012	0.10	0.30	
F	.031	.045	0.80	1.15	

### Electrical Characteristics @ 25°C Unless Otherwise Specified

Mean Rectifying Current	$I_O$	0.5A	$T_A = 25^\circ\text{C}$
Peak Forward Surge Current	$I_{FSM}$	1000mA	8.3ms, half sine
Maximum Forward Voltage Drop Per Element	$V_F$	0.47V 0.36V	$T_A = 25^\circ\text{C}$ $I_{FM} = 500\text{mA}$ $I_{FM} = 100\text{mA}$
Maximum DC Reverse Current At Rated DC Blocking Voltage	$I_R$	30 $\mu$ A	$T_A = 25^\circ\text{C}$ $V_R = 10\text{V}$

### Suggested Solder Pad Layout



# MC551-30

## RATING AND CHARACTERISTIC CURVES

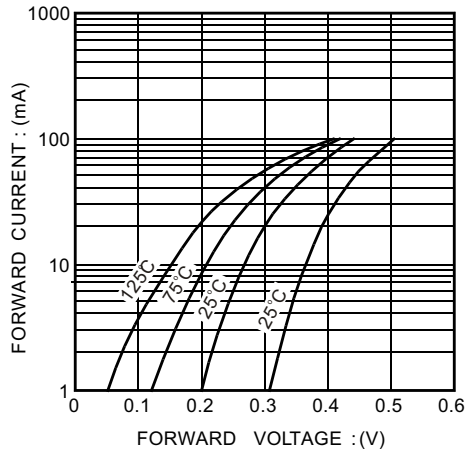


Fig. 1 Forward characteristics

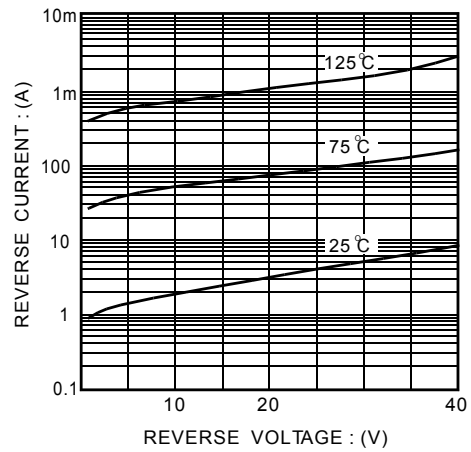


Fig. 2 Reverse characteristics

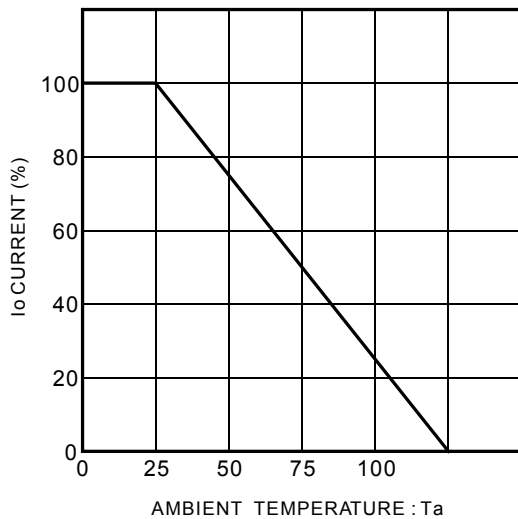


Fig. 4 Derating curve  
(mounting on glass epoxy PCBs)

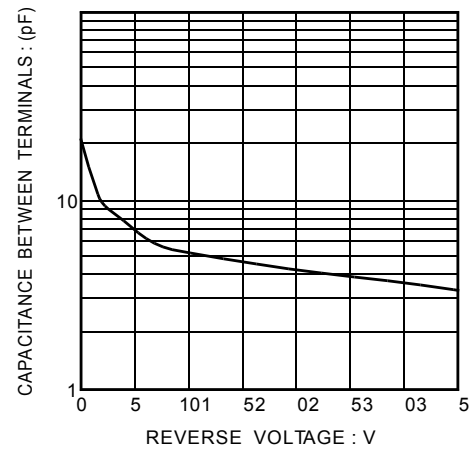


Fig. 3 Capacitance between terminals characteristics